New Insights into Additive Manufacturing of Intelligent Materials

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Message from the Guest Editor

This scholarly exploration seeks to elucidate the intricate interplay between additive manufacturing, intelligent materials, and artificial intelligence (AI) technologies. Contributions to this issue are invited to scrutinize the development of responsive smart materials, employing sophisticated sensors and actuators, as well as pioneering applications of multi-material printing techniques. Furthermore, research endeavors are encouraged to harness AI algorithms for the optimization of design, thereby augmenting the efficiency and precision of additive manufacturing processes.

The transformative potential of AI integration with additive manufacturing is poised to revolutionize the manufacturing industry. Accordingly, this Special Issue endeavors to furnish novel insights into this evolving landscape. Researchers and practitioners are invited to contribute to this intellectual discourse, thereby advancing the collective knowledge and understanding of the domain of additive manufacturing of intelligent materials.

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Special Issue

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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